

Product Change Notification - JAON-30NGXA111

Date:

31 Jan 2020

Product Category:

Interface- LIN Transceiver; Interface- Controller Area Network (CAN)

Affected CPNs:



Notification subject:

CCB 4036 and 4036.001 Initial Notice: Qualification of MTAI as an additional assembly site for selected Atmel products of the 77k wafer technology available in 8L and 14L SOIC packages.

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MTAI as an additional assembly site for selected Atmel products of the 77k wafer technology available in 8L and 14L SOIC packages.

Pre Change:

<u>For 14L SOIC package:</u> Assembled at ASSH assembly site using EN-4900GC die attach and G700 mold compound material.

<u>For 8L SOIC package:</u> Assembled at ANAP assembly site using 8290 die attach and G700 mold compound material.

Post Change:

<u>For 14L SOIC package:</u> Assembled at ASSH assembly site using EN-4900GC die attach and G700 mold compound material or assembled at MTAI using 8390A die attach and G600V mold compound material.

<u>For 8L SOIC package:</u> Assembled at ANAP assembly site using 8290 die attach and G700 mold compound material or assembled at MTAI using 8390A die attach and G600V mold compound material.

Pre and Post Change Summary:

For 14L SOIC Package:

	Pre Change	Post C	hange			
			Microchip Technology			
Assembly Site	ASE-Shanghai (ASSH)	ASE-Shanghai (ASSH)	Thailand			
	,		(HQ) (MTAI)			
Wire material	CuPdAu	CuPdAu	CuPdAu			
Die attach material	EN-4900GC	EN-4900GC	8390A			
Molding compound	6700	0700	C600V			
material	G700	G700	G600V			
Lead frame material	CDA194	CDA194	CDA194			
Lead Plating	NiPd-AgPd	NiPd-AgPd	Matte Tin			



	Pre Change	Post Change					
			Microchip Technology				
Accomply Site	Amkor Technology	Amkor Technology	Thailand				
Assembly Site	Philippine (ANAP)	Philippine (ANAP)					
	, , , , ,	, , , , ,	(HQ) (MTAI)				
Wire material	CuPdAu	CuPdAu	CuPdAu				
Die attach material	8290	8290	8390A				
Molding compound	G700	G700	G600V				
material	G700	G700	G000V				
Lead frame material	CDA194	CDA194	CDA194				
Lead Plating	NiPd-AgPd	NiPd-AgPd	Matte Tin				

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None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

August 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

		Jan	uary 2	2020		,	August 2020					
Workweek	01	02	03	04	05	->	32	33	34	35	36	
Initial PCN Issue Date					Х							
Qual Report Availability							Χ					
Final PCN Issue Date							X					

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

January 31, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN JAON-30NGXA111 Qual Plan.pdf



notification.

Terms and Conditions:

make the applicable selections.

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN home page</u> select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and

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Affected Catalog Part Numbers (CPN)

ATA663211-GAQW

ATA663254-GAQW

ATA663254-GAQW-VAO

ATA6562-GAQW0

ATA6566-GAQW0

ATA6563-GAQW0

ATA6564-GAQW0

ATA6562-GAQW1

ATA6561-GAQW

ATA6560-GAQW

ATA6564-GAQW1

ATA6563-GAQW1

ATA6566-GAQW1

ATA6560-GAQW-N

ATA6561-GAQW-N

ATA6560-GAQW-VAO

ATA6625-GAQW

ATA6570-GNQW0

ATA6570-GNQW1

Date: Thursday, January 30, 2020